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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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STH13009

High voltage fast-switching NPN power transistor

Preliminary data

Features

- High voltage capability
- Low spread of dynamic parameters
- Very high switching speed

Applications

Switching mode power supplies

Description

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds anh high voltage capability. It uses a Hollow Emitter structure to enhance switching speeds.

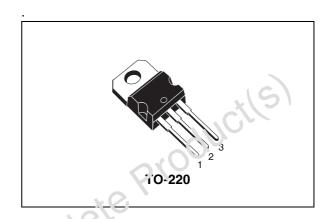


Figure 1. Internal schematic diagram

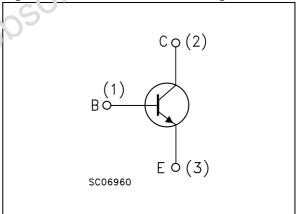


Table 1. Device summary

Ord	der code	Marking	Package	Packaging
ST	H13009	H13009	TO-220	Tube

1 Absolute maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CEV}	Collector-emitter voltage (V _{BE} = -1.5V)	700	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	400	V
V _{EBO}	Emitter-base voltage (I _C = 0)	12	V
Ic	Collector current	12	Α
I _{CM}	Collector peak current (t _p < ms)	24	1
I _B	Base current	6	A
I _{BM}	Base peak current (t _p < ms)	12	Α
P _{TOT}	Total dissipation at T _{case} = 25°C	120	W
T _{stg}	Storage temperature	65 to 150	°C
T _J	Max. operating junction temperature	150	°C

Table 3. Thermal data

	Symbol	Parameters		Value	Unit
	R _{thj-case}	Thermal resistance junction case	max	1.25	°C/W
		ci(s)			
	010	OGINE			
-105018	16,				
Opso					

Electrical characteristics 2

(T_{case} = 25°C; unless otherwise specified)

Table 4. **Electrical characteristics**

Symbol	Parameter	Test co	onditions	Min.	Тур.	Max.	Uni
I _{CEV}	Collector cut-off current	V _{CE} = 700 V	T 100°C			10	μΑ
	(V _{BE} = -1.5V)	V _{CE} = 700 V	T _C = 100°C			500	μA
I _{EBO}	Emitter cut-off current (I _C = 0)	V _{EB} = 10 V				10	μΑ
V _{CEO(sus)} ⁽¹⁾	Collector-emitter sustaining voltage (I _B = 0)	I _C = 10 mA		400	M		V
		I _C = 4 A	I _B = 0.8 A		0.2	0.5	٧
v (1)	Collector-emitter	I _C = 5 A	I _B = 1 A		0.25	0.6	V
V _{CE(sat)} ⁽¹⁾	saturation voltage	I _C = 8 A	I _B = 1.0 A		0.35	1	V
		I _C = 12 A	'g:: 2.4 A		0.6	2	V
(4)	Base-emitter saturation	I _C = 5 A	I _B = 1 A			1.2	٧
$V_{BE(sat)}^{(1)}$	voltage	1C = 3 1.	$I_{B} = 1.6 A$			1.6	٧
. (1)		I _C = 5 A	V _{CE} =5 V	18		30	
h _{FE} ⁽¹⁾	DC current gain	I _C = 8 A	$V_{CE} = 5 V$	11		23	
	Inductive load	V _{CC} = 250 V	I _C = 5A				
	Ctorogo tura	I _{B1} = 1 A	$I_{B2} = -2 A$		1.7	2.5	μs
t _s	Storage time	'BI- ' '	-02				

Electrical characteristics STH13009

2.1 Electrical characteristic (curves)

Figure 2. Safe operating area

Figure 3. Derating curve

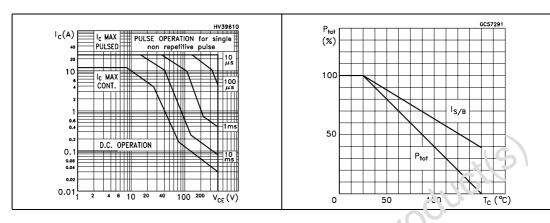


Figure 4. DC current gain

Figure 5. DC current gain

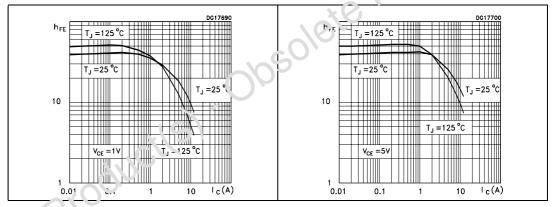


Figure 6. Collector-emitter saturation voltage

Figure 7. Base-emitter saturation voltage

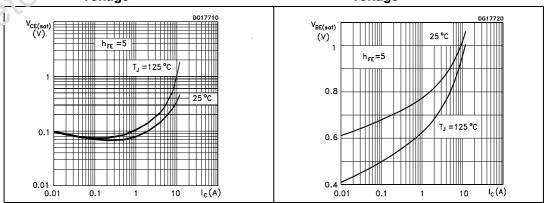
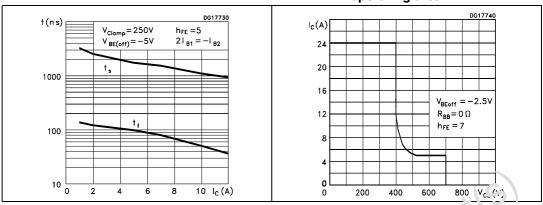
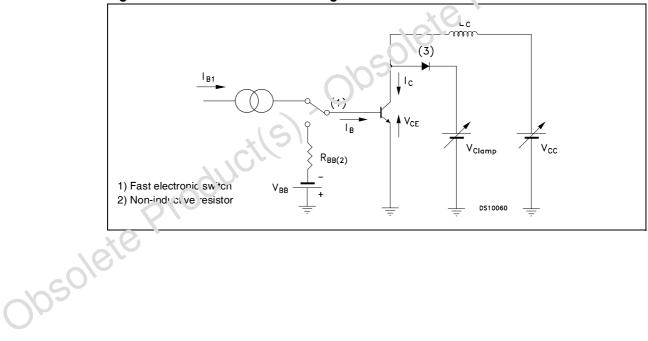


Figure 8. Inductive load switching time Figure 9. Reverse biased safe operating area



2.2 Test circuit

Figure 10. Inductive load switching test circuit

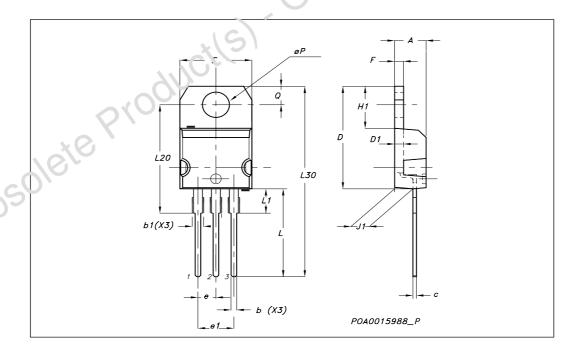


3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available Obsolete Product(s). at: www.st.com

TO-220 Mechanical data

	mm.				
DIM.	MIN.	ТҮР	MAX.		
Α	4.40		4.60		
b	0.61		0.88		
b1	1.14		1.70		
С	0.49		0.70		
D	15.25		15.75		
D1		1.27	1.0		
E	10		10.40		
е	2.40		2.70		
e1	4.95		5.1.		
F	1.23		1.32		
H1	6.20		6 60		
J1	2.40		2.72		
L	13		14		
L1	3.50	- 1	3.93		
L20		16.40			
L30		28.90			
øΡ	3.75	105	3.85		
Q	2.65		2.95		



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Revision history STH13009

4 Revision history

Table 5. Document revision history

Date	Revision	Changes
15-Oct-2007	1	Initial Release

Obsolete Product(s)

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